

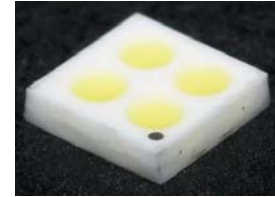
Chip Array on Ceramic LED Light Source



INTRODUCTION OF CHIP ARRAY ON CERAMIC TYPE SMD LED

Model : C3535-04003-CW/NW/WS/WT

CETUS™ provides the leading Chip Array on Ceramic type of LED technology for high efficiency solid-state lighting solutions. It offers excellent uniformity, flexibility and cost efficiency along with compact size and wide range of color selections. All components are produced by packing high-performance LED chips and silicon resin with proprietary Intematix phosphors.



Features and Benefits

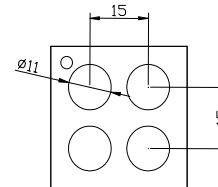
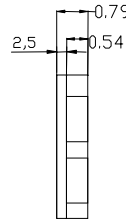
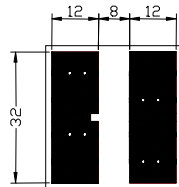
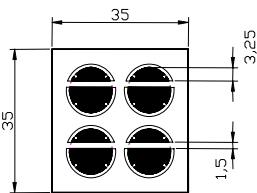
- Ideal for LED lighting application to avoid multi-shadows
- Higher heat conductivity for better thermal management
- Provide variable and innovative array LED layout designs and combinations
- Reduce the initial development cost and time
- High lumen-performance per dollar cost
- Lead free reflow solder compatible with RoHS compliant

1. Dimensions and Materials

Dimensions: 3.5mm x 3.5 mm x 0.9 mm
 Packages: Ceramics
 Capsulated Resin: Silicone Resin with Silicate Phosphor
 Electrodes: Ag Plating
 Chips: 4 chips packed in 4 cavities

2. Applications

Solid State Lighting
 Indoor/Outdoor/Decoration
 Signal Light Engine
 Commercial Display
 Industrial Light Engine

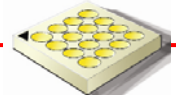


3. Initial Electrical/Optical Characteristics

(Thermal Pad Temperature @25°C)

ITEM	SYMBOL	TEST CONDITIONS	UNIT	MIN.	TYP.	MAX.
Forward Voltage	V _f	100mA	V	3	3.5	3.8
Reverse Current	I _r	5V	μA	0		5
Luminous Flux for CW	φ _v	100mA	Lm	18	20.5	23
Luminous Flux for NW	φ _v	100mA	lm	16	18.5	21
Luminous Flux for WS	φ _v	100mA	lm	14	16	18
Luminous Flux for WT	φ _v	100mA	lm	13	14.5	16

- Luminous flux performance measured upon published operating conditions or test methods.
- According to the luminous flux and/or specific radiometric power levels products. Please consult Intematix Technology Center for more information.
- Measurement uncertainty of the luminous intensity and power: ±8%
- Reference for typical thermal resistance junction to thermal pad (R_{θj-c}) ≤ 9 °C/W
- Typical viewing angle 2θ 1/2: 110 degree



4. Absolute Maximum Ratings

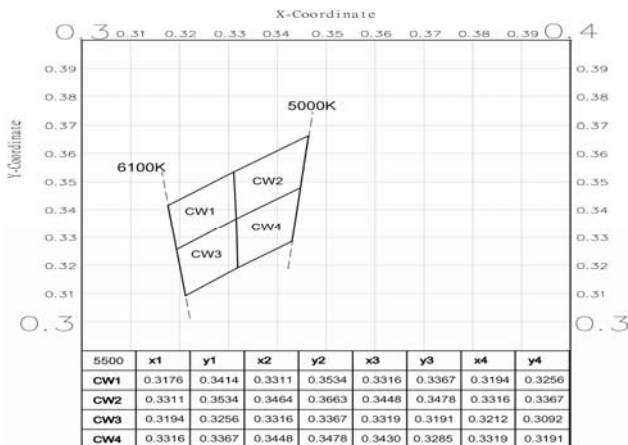
(Thermal Pad Temperature @25°C)

ITEM	SYMBOL	ABSOLUTE MAXIMUM RATING	UNIT
Forward current	I _f	100	mA
Reverse Voltage	V _r	5	V
Power Dissipation	P _d	0.3	W
Operating Temperature	T _{opr}	-25~+100	°C
Storage Temperature	T _{stg}	- 40~+100	°C
Soldering Temperature (Reflow)	T _{sl}	max.240 < 5sec	°C
Soldering Temperature (Hand)	T _{sl}	max.350 < 3sec	°C

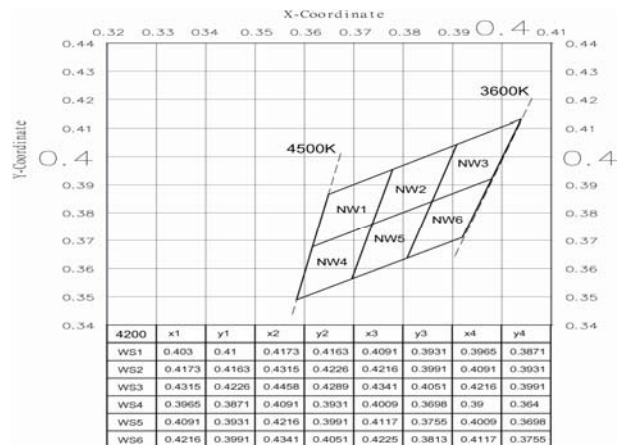
- I_f conditions: /10 Duty Cycle & 0.1ms for pulse width.
- Reflow method: 1.6mm from body for 5 seconds without over the published maximum temperature.
- maximum driving current depends on junction temperature, die attach methods/materials, and lifetime requirements of the customer's application.

5. White Color Temperature Ranks (Refer to CIE 1931 chromaticity diagram)

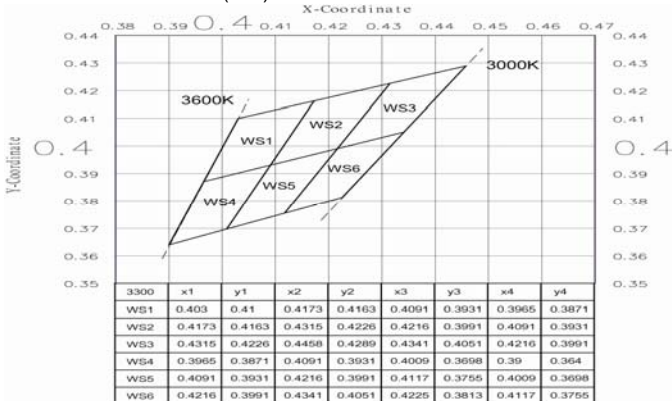
Cool White (CW) bin structures and coordinates



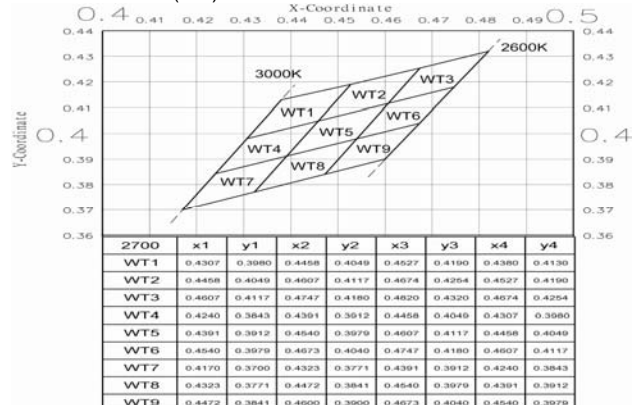
Neutral White (NW) bin structures and coordinates



Warm White (WS) bin structures and coordinates



Warm White (WT) bin structures and coordinates



- Color coordinates measurement allowance is ± 0.01
- According to higher/lower color temperature ranks, please contact Intematix Technology Center for further information.
- Thermal Pad Temperature @25°C @400mA